

Transient Voltage Suppressors / ESD Protectors

Features

- Two, three, four, five, or six transient voltage suppressors
- Compact SMT package saves board space and facilitates layout in space-critical applications
- In-system ESD protection to 20kV contact discharge, per the IEC 61000-4-2 international standard
- Lead-free versions available

Applications

- ESD protection of PC ports, including USB ports, serial ports, parallel ports, IEEE1394 ports, docking ports, proprietary ports, etc.
- Protection of interface ports or IC pins which are exposed to high ESD levels

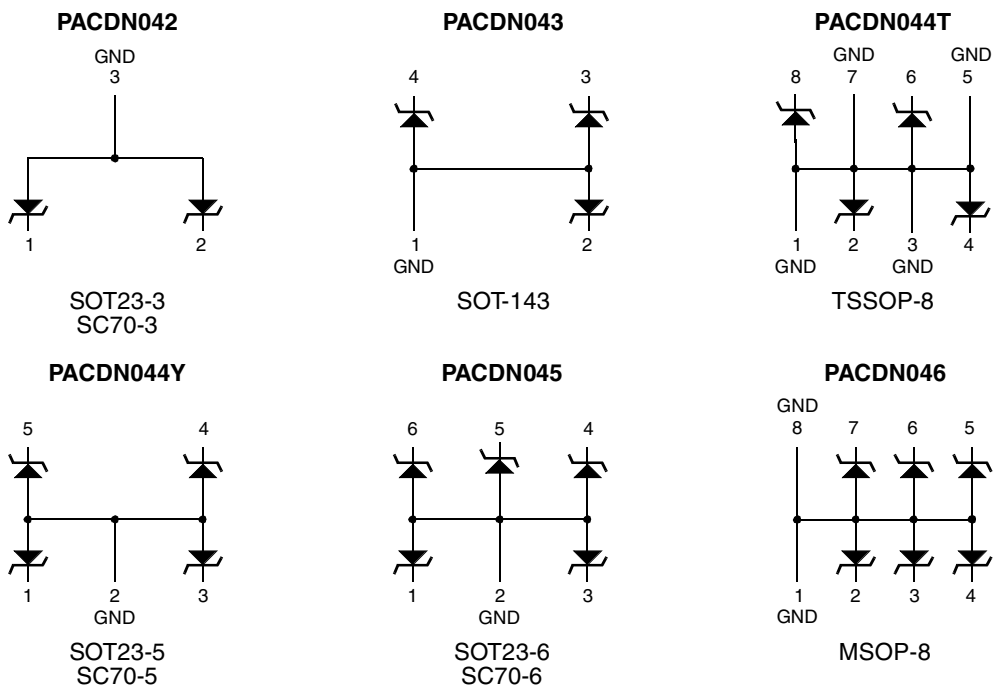
Product Description

The family of devices consists of the PACDN042, PACDN043, PACDN044, PACDN045, and PACDN046. These devices are transient voltage suppressor arrays that provide a very high level of protection for sensitive electronic components which may be subjected to electrostatic discharge (ESD). The PACDN042/43/44/45/46 devices are designed and characterized to dissipate safely ESD strikes that exceed IEC 61000-4-2 International Standard Level 4 (8kV contact discharge).

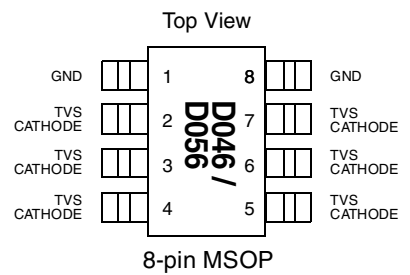
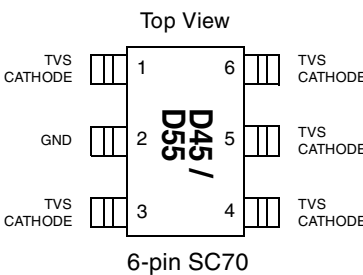
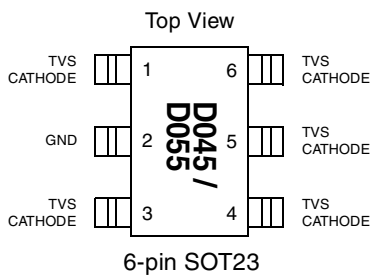
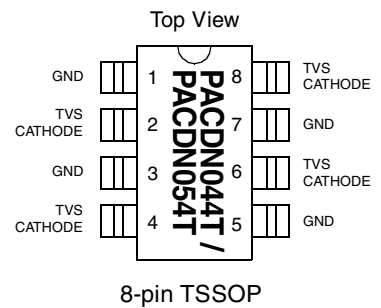
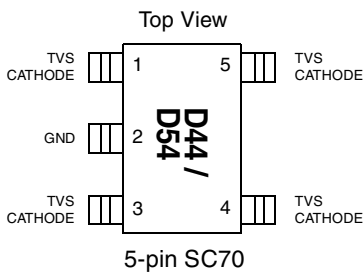
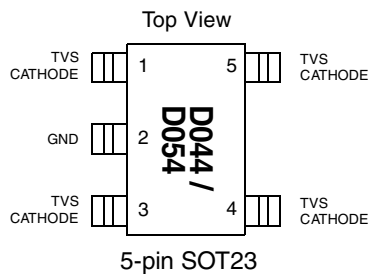
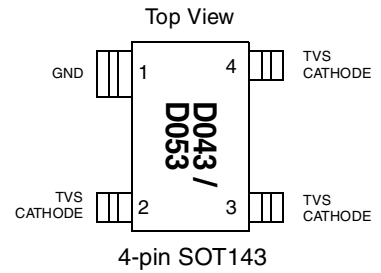
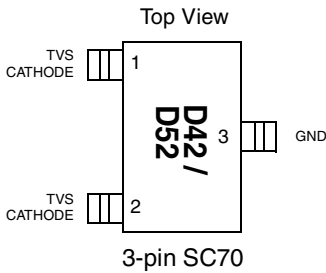
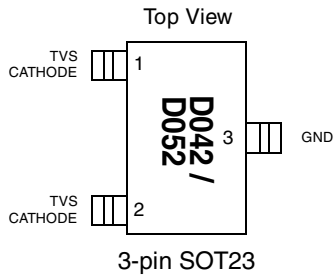
All pins are rated to withstand 20kV ESD pulses using the IEC 61000-4-2 contact discharge method. Using the MIL-STD-883D (Method 3015) specification for Human Body Model (HBM) ESD, all pins are protected from contact discharges of greater than 30kV.

The PACDN042/43/44/45/46 is available with lead-free finishing, supporting the current global industry movement to lead free manufacturing.

Electrical Schematic



PACKAGE / PINOUT DIAGRAMS



Note: SOT23, SC70, SOT143, TSSOP, and MSOP packages may differ in size. These drawings are not to scale.

PIN DESCRIPTIONS

PINS	NAME	DESCRIPTION
(Refer to package outline drawings)	TVS Cathode	The cathode of the respective TVS diode, which should be connected to the node requiring transient voltage protection.
(Refer to package outline drawings)	GND	The anode of the TVS diodes.



Ordering Information

PART NUMBERING INFORMATION					
Bumps	Package	Standard Finish		Lead-free Finish ²	
		Ordering Part Number ¹	Part Marking	Ordering Part Number ¹	Part Marking
3	SOT23-3	PACDN042Y3	D042	PACDN042Y3R	D052
3	SC70-3	PACDN042YB3	D42	PACDN042YB3R	D52
4	SOT143	PACDN043Y4	D043	PACDN043Y4R	D053
5	SOT23-5	PACDN044Y5	D044	PACDN044Y5R	D054
5	SC70-5	PACDN044YB5	D44	PACDN044YB5R	D54
6	SOT23-6	PACDN045Y6	D045	PACDN045Y6R	D055
6	SC70-6	PACDN045YB6	D45	PACDN045YB6R	D55
8	TSSOP	PACDN044T	PACDN044T	PACDN044TR	PACDN054T
8	MSOP	PACDN046M	D046	PACDN046MR	D056

Note 1: Parts are shipped in Tape & Reel form unless otherwise specified.

Specifications

ABSOLUTE MAXIMUM RATINGS		
PARAMETER	RATING	UNITS
Storage Temperature Range	-65 to +150	°C
Package Power Dissipation		
SC70	0.2	W
SOT23-3, SOT23-5, SOT23-6, SOT143	0.225	W
TSSOP, MSOP	0.5	W

STANDARD OPERATING CONDITIONS		
PARAMETER	RATING	UNITS
Operating Temperature	-40 to +85	°C



Specifications (cont'd)

ELECTRICAL OPERATING CHARACTERISTICS						
SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
C	Capacitance	$T_A = 25^\circ\text{C}$, 2.5VDC, 1MHz		30		pF
V_{RSO}	Reverse Stand-off Voltage	$I_R = 10\mu\text{A}$, $T_A = 25^\circ\text{C}$	5.5			V
		$I_R = 1\text{mA}$, $T_A = 25^\circ\text{C}$	6.1			V
I_{LEAK}	Leakage Current	$V_{\text{IN}} = 5.0\text{VDC}$, $T_A = 25^\circ\text{C}$		1	100	nA
V_{SIG}	Small Signal Clamp Voltage Positive Clamp Negative Clamp	$I = 10\text{mA}$, $T_A = 25^\circ\text{C}$	6.2	6.8	8	V
		$I = -10\text{mA}$, $T_A = 25^\circ\text{C}$	-0.4	-0.8	-1.2	V
V_{ESD}	ESD Withstand Voltage Human Body Model, MIL-STD-883, Method 3015 Contact Discharge per IEC 61000-4-2 standard	Notes 1 & 2	± 30			kV
		Notes 1 & 2	± 20			kV
V_{CL}	Clamping Voltage during ESD Discharge +8kV Discharge -8kV Discharge	MIL-STD-883D, Method 3015		12		V
				-8		V
R_D	Diode Dynamic Resistance Forward Conduction Reverse Conduction			1.0		Ω
				1.4		Ω

Note 1: Guaranteed by design and characterization.

Note 2: ESD voltage applied between channel pins & ground, one pin at a time; all other channel pins open; all GND pins grounded.

Performance Information

Diode Capacitance

Typical diode capacitance with respect to positive TVS cathode voltage (reverse voltage across the diode) is given in Figure 1.

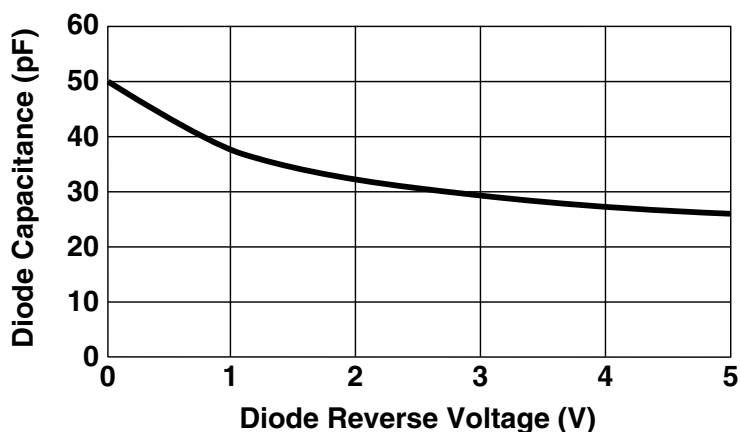
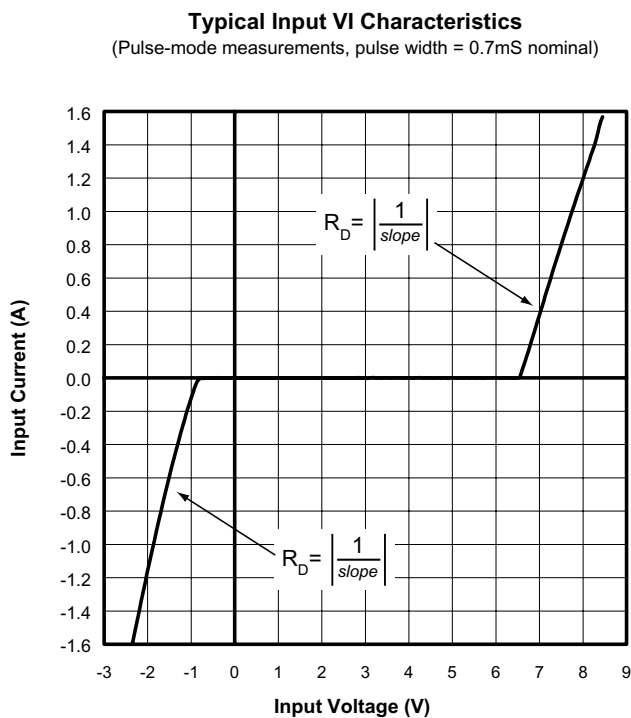


Figure 1. Diode Capacitance vs. Reverse Voltage

Typical High Current Diode Characteristics

Measurements are made in pulse mode with a nominal pulse width of 0.7mS.



Mechanical Details

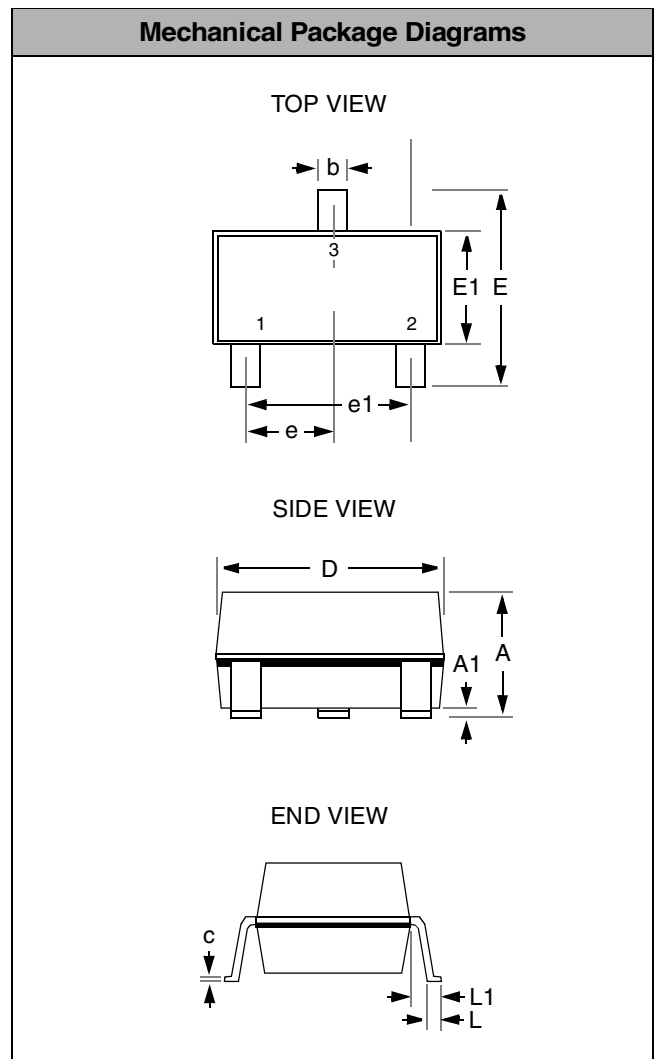
PACDN042/43/44/45/46 devices are packaged in the following packages: SOT23-3, SOT23-5, SOT23-6, SC70-3, SC70-5, SC70-6, SOT143, TSSOP-8, and MSOP-8.

SOT23-3 Mechanical Specifications

Dimensions for PACDN042Y3 and PACDN042Y3R devices packaged in 3-pin SOT23 packages are presented below.

For complete information on the SOT23-3 package, see the California Micro Devices SOT23 Package Information document.

PACKAGE DIMENSIONS				
Package	SOT23-3 (JEDEC name is TO-236)			
Pins	3			
Dimensions	Millimeters		Inches	
	Min	Max	Min	Max
A	0.89	1.12	0.0350	0.0441
A1	0.01	0.10	0.0004	0.0039
b	0.30	0.50	0.0118	0.0197
c	0.08	0.20	0.0031	0.0079
D	2.80	3.04	0.1102	0.1197
E	2.10	2.64	0.0827	0.1039
E1	1.20	1.40	0.0472	0.0551
e	0.95 BSC		0.0374 BSC	
e1	1.90 BSC		0.0748 BSC	
L	0.40	0.60	0.0157	0.0236
L1	0.54 REF		0.0213 REF	
# per tape and reel	3000 pieces			
Controlling dimension: millimeters				



Package Dimensions for SOT23-3.

Mechanical Details (continued)

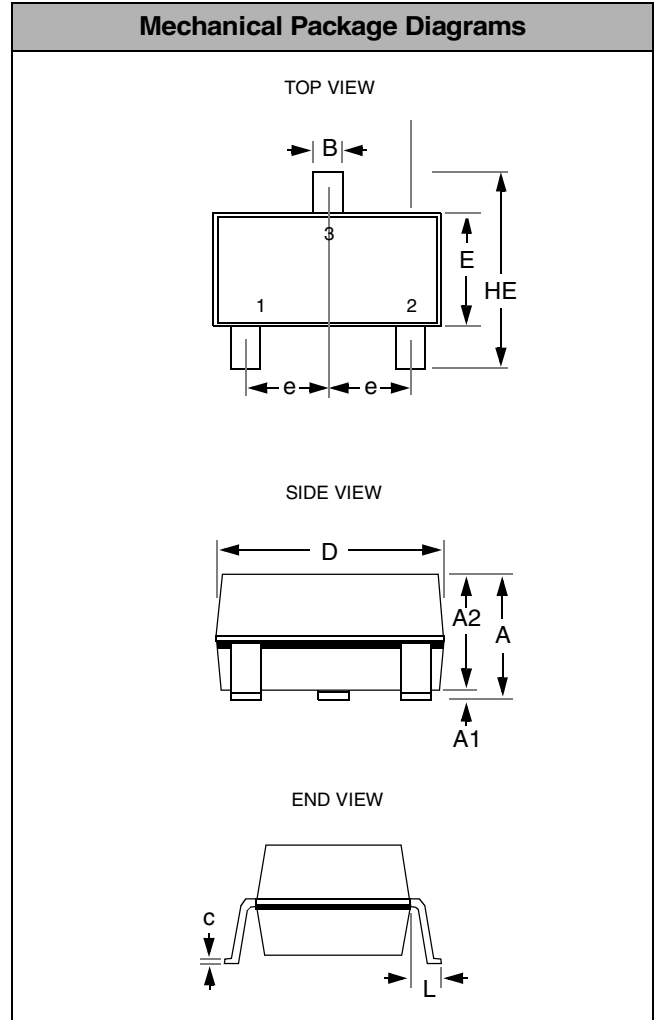
SC70-3 Mechanical Specifications:

Dimensions for PACDN042YB3 and PACDN042YB3R devices packaged in 3-pin SC70 packages are presented below.

For complete information on the SC70-3 package, see the California Micro Devices SC70 Package Information document.

PACKAGE DIMENSIONS		
Package	SC70 (JEDEC name is MO-203 Issue A)	
Pins	3	
Dimensions	Millimeters	
	Min	Max
A	0.80	1.10
A1	0.00	0.10
A2	0.70	1.00
B	0.15	0.30
c	0.08	0.25
D	1.85	2.25
E	1.15	1.35
e	0.65 BSC	
HE	2.00	2.40
L	0.26	0.46
# per bag	1000 pieces*	
# per tape and reel	3000 pieces*	

* This is an approximate amount which may vary.



Package Dimensions for SC70-3.

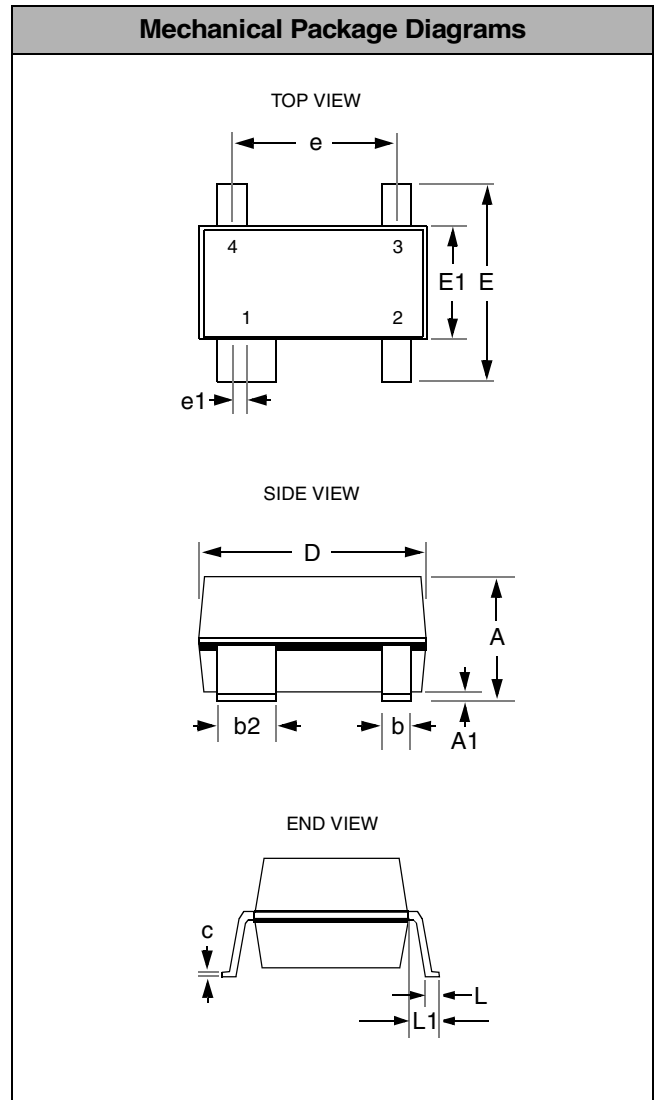
Mechanical Details (continued)

SOT143 Mechanical Specifications

Dimensions for PACDN043Y4 and PACDN043Y4R devices packaged in 4-pin SOT143 packages are presented below.

For complete information on the SOT143 package, see the California Micro Devices SOT143 Package Information document.

PACKAGE DIMENSIONS				
Package	SOT143			
Pins	4			
Dimensions	Millimeters		Inches	
	Min	Max	Min	Max
A	0.80	1.22	0.031	0.048
A1	0.05	0.15	0.002	0.006
b	0.30	0.50	0.012	0.019
b2	0.76	0.89	0.030	0.035
c	0.08	0.20	0.003	0.008
D	2.80	3.04	0.110	0.119
E	2.10	2.64	0.082	0.103
E1	1.20	1.40	0.047	0.055
e	1.92 BSC		0.075 BSC	
e1	0.20 BSC		0.008 BSC	
L	0.4	0.6	0.016	0.024
L1	0.54 REF		0.021 REF	
# per tape and reel	3000 pieces*			
Controlling dimension: millimeters				



Package Dimensions for SOT143.

* This is an approximate amount which may vary.



Mechanical Details (continued)

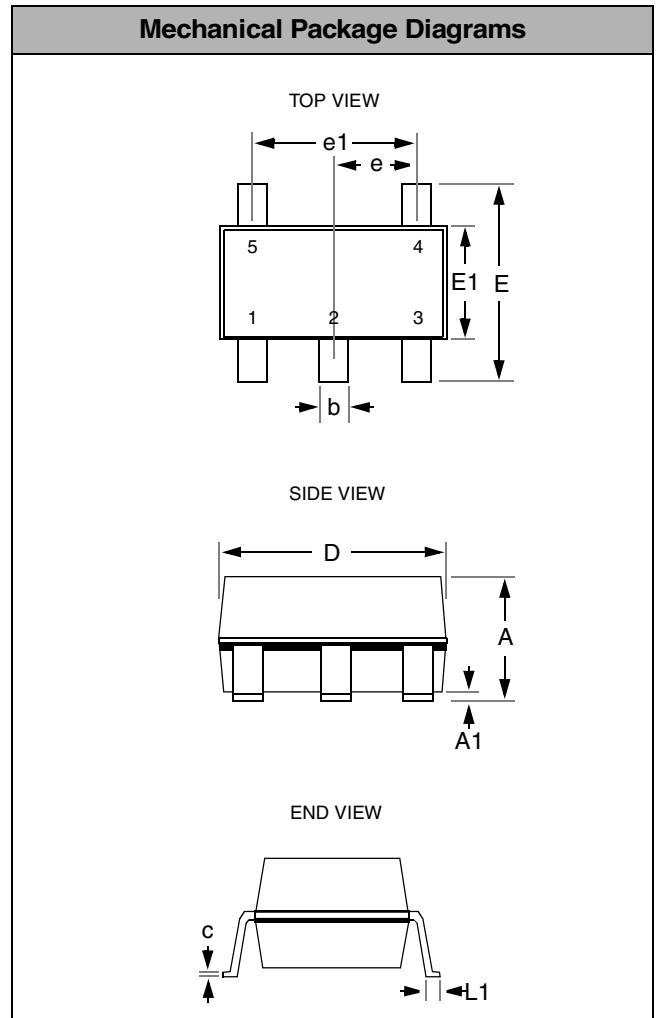
SOT23-5 Mechanical Specifications

Dimensions for PACDN044Y5 and PACDN044Y5R devices packaged in 5-pin SOT23 packages are presented below.

For complete information on the SOT23-5 package, see the California Micro Devices SOT23 Package Information document.

PACKAGE DIMENSIONS				
Package	SOT23-5 (JEDEC name is MO-178)			
Pins	5			
Dimensions	Millimeters		Inches	
	Min	Max	Min	Max
A	--	1.45	--	0.057
A1	0.00	0.15	0.000	0.006
b	0.30	0.50	0.012	0.020
c	0.08	0.22	0.003	0.009
D	2.75	3.05	0.108	0.120
E	2.60	3.00	0.102	0.118
E1	1.45	1.75	0.057	0.069
e	0.95 BSC		0.0374 BSC	
e1	1.90 BSC		0.0748 BSC	
L	0.60 REF		0.0236 REF	
# per tape and reel	3000 pieces*			
Controlling dimension: inches				

* This is an approximate amount which may vary.



Package Dimensions for SOT23-5.

Mechanical Details (continued)

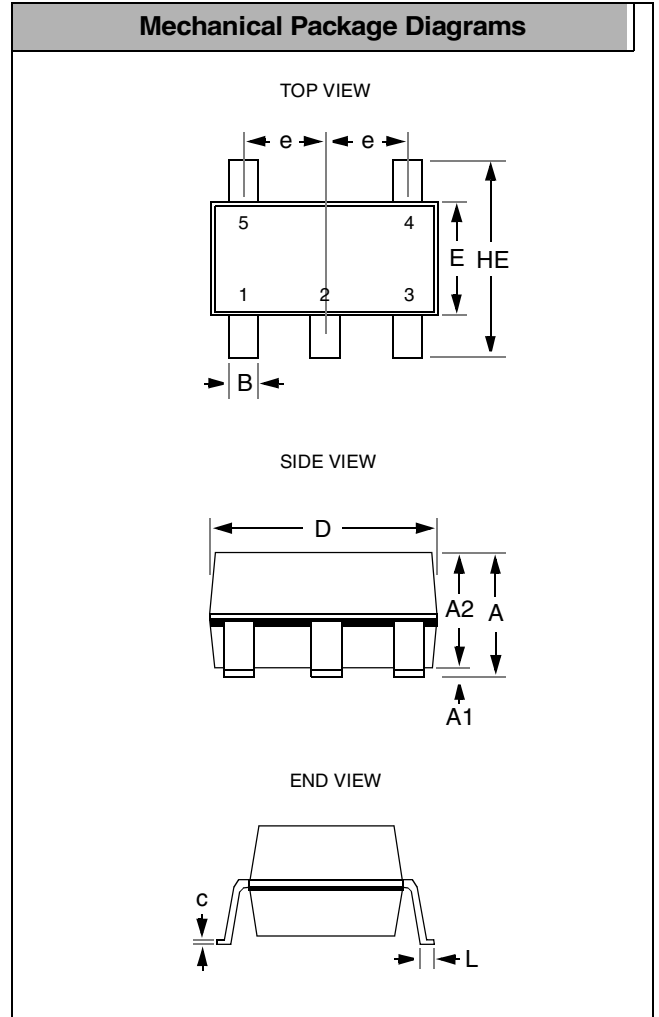
SC70-5 Mechanical Specifications:

Dimensions for PACDN044YB5 and PACDN044YB5R devices packaged in 5-pin SC70 packages are presented below.

For complete information on the SC70-5 package, see the California Micro Devices SC70 Package Information document.

PACKAGE DIMENSIONS		
Package	SC70-5 (JEDEC name is MO-203 Issue A)	
Pins	5	
Dimensions	Millimeters	
	Min	Max
A	0.80	1.10
A1	0.00	0.10
A2	0.70	1.00
B	0.15	0.30
c	0.08	0.25
D	1.85	2.25
E	1.15	1.35
e	0.65 BSC	
HE	2.00	2.40
L	0.26	0.46
# / bag	1000 pieces*	
# / tape and reel	3000 pieces*	

* This is an approximate amount which may vary.



Package Dimensions for SC70-5

Mechanical Details (continued)

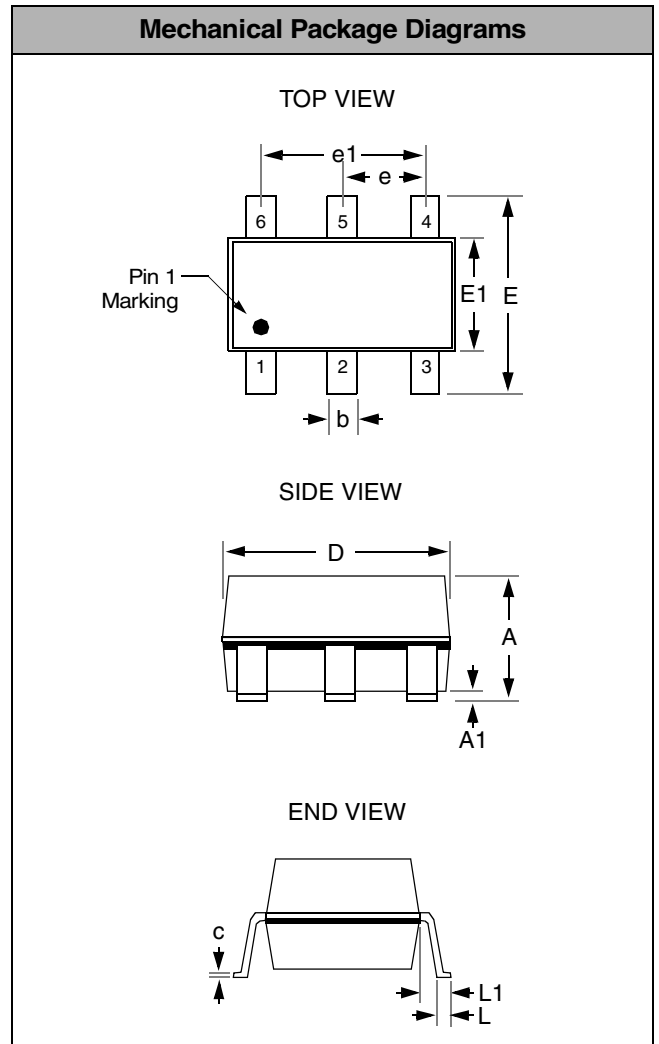
SOT23-6 Mechanical Specifications:

Dimensions for PACDN045Y6 and PACDN045Y6R devices packaged in 6-pin SOT23 packages are presented below.

For complete information on the SOT23-6 package, see the California Micro Devices SOT23 Package Information document.

PACKAGE DIMENSIONS				
Package	SOT23 (JEDEC name is MO-178)			
Pins	6			
Dimensions	Millimeters		Inches	
	Min	Max	Min	Max
A	--	1.45	--	0.057
A1	0.00	0.15	0.000	0.006
b	0.30	0.50	0.012	0.020
c	0.08	0.22	0.003	0.009
D	2.75	3.05	0.108	0.120
E	2.60	3.00	0.102	0.118
E1	1.45	1.75	0.057	0.069
e	0.95 BSC		0.0374 BSC	
e1	1.90 BSC		0.0748 BSC	
L	0.60 REF		0.0236 REF	
# per tape and reel	3000 pieces*			
Controlling dimension: inches				

* This is an approximate amount which may vary.



Package Dimensions for SOT23-6.

Mechanical Details (continued)

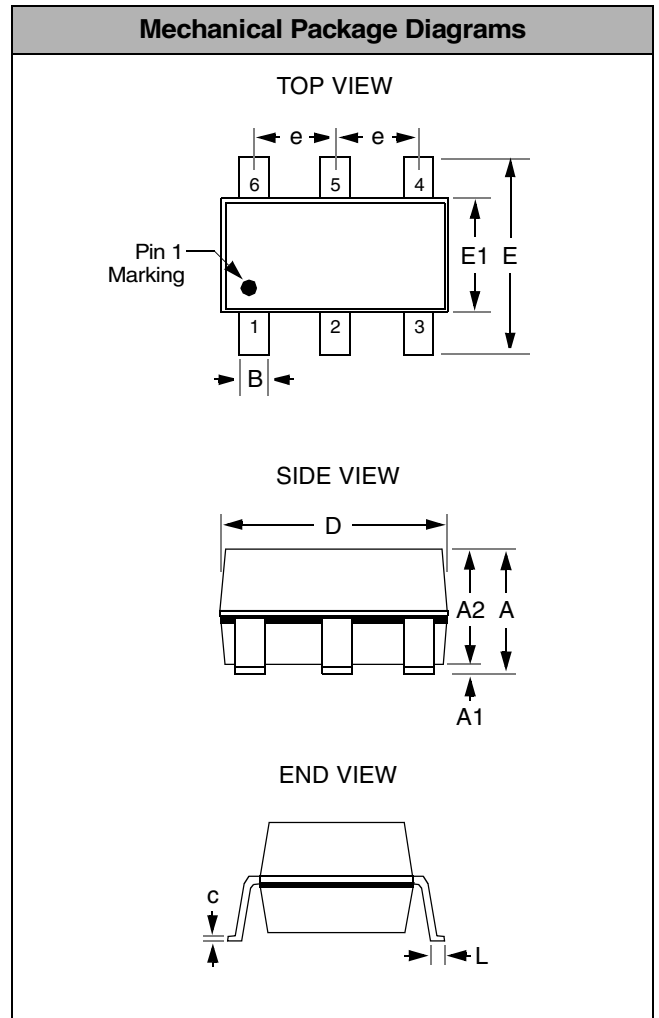
SC70-6 Mechanical Specifications:

Dimensions for PACDN045YB6 and PACDN045YB6R devices packaged in 6-pin SC70 packages are presented below.

For complete information on the SC70-6 package, see the California Micro Devices SC70 Package Information document.

PACKAGE DIMENSIONS		
Package	SC70-6 (JEDEC name is MO-203 Issue A)	
Pins	6	
Dimensions	Millimeters	
	Min	Max
A	0.80	1.10
A1	0.00	0.10
A2	0.70	1.00
B	0.15	0.30
c	0.08	0.25
D	1.85	2.25
E	1.15	1.35
e	0.65 BSC	
HE	2.00	2.40
L	0.26	0.46
# / bag	1000 pieces*	
# / tape and reel	3000 pieces*	

* This is an approximate amount which may vary.



Package Dimensions for SC70-6.

Mechanical Details (continued)

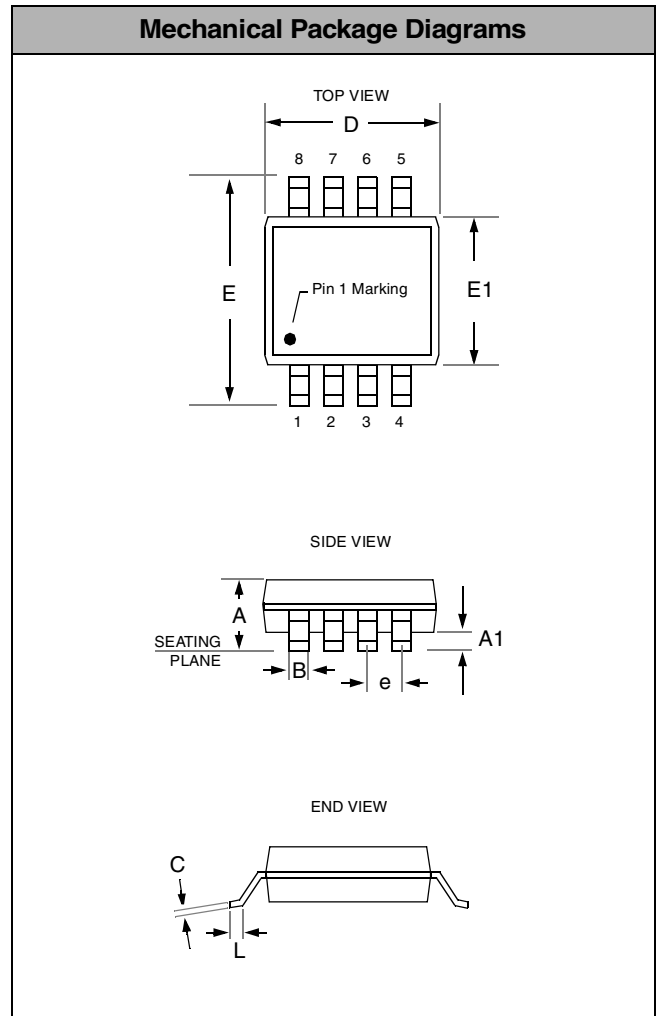
TSSOP-8 Mechanical Specifications:

Dimensions for PACDN044T and PACDN044TR devices packaged in 8-pin TSSOP packages are presented below.

For complete information on the TSSOP-8 package, see the California Micro Devices TSSOP Package Information document.

PACKAGE DIMENSIONS				
Package	TSSOP			
Pins	8			
Dimensions	Millimeters		Inches	
	Min	Max	Min	Max
A	—	1.10	—	0.0433
A1	0.05	0.15	0.002	0.006
B	0.19	0.30	0.0075	0.0118
C	0.09	0.20	0.0035	0.0079
D	2.90	3.10	0.114	0.122
E	6.25	6.50	0.246	0.256
E1	4.30	4.50	0.169	0.177
e	0.65 BSC		0.0256 BSC	
L	0.50	0.70	0.020	0.028
# per tube	74 pcs*			
# per tape and reel	2500 pcs			
Controlling dimension: millimeters				

* This is an approximate amount which may vary.



Package Dimensions for TSSOP-8



Mechanical Details (continued)

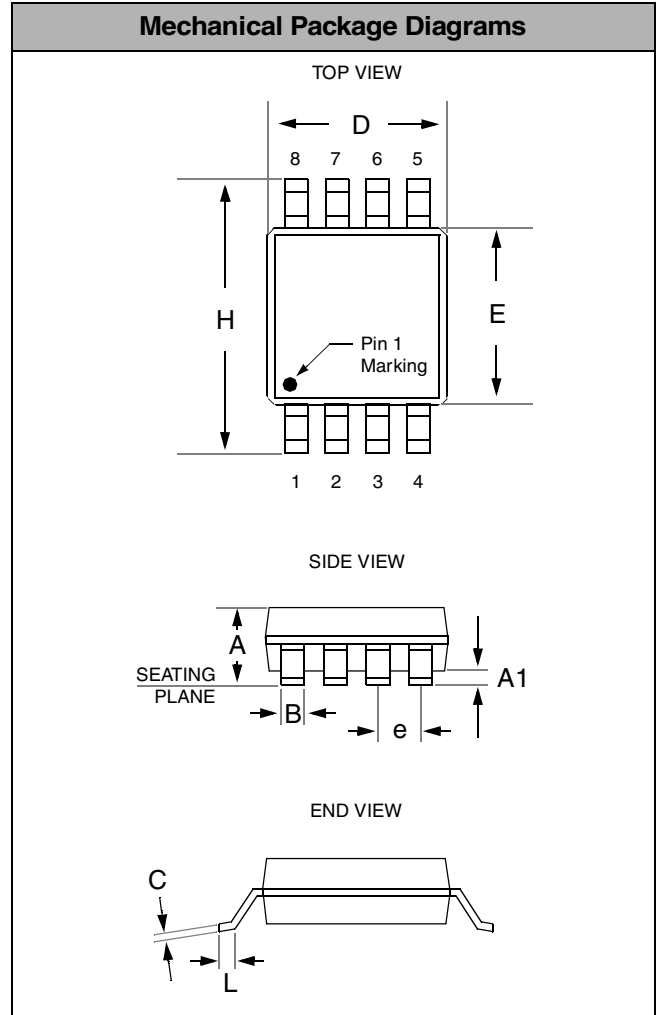
MSOP-8 Mechanical Specifications:

Dimensions for PACDN046M and PACDN046MR devices packaged in 8-pin MSOP packages are presented below.

For complete information on the MSOP-8 package, see the California Micro Devices MSOP Package Information document.

PACKAGE DIMENSIONS				
Package	MSOP			
Pins	8			
Dimensions	Millimeters		Inches	
	Min	Max	Min	Max
A	0.87	1.17	0.034	0.046
A1	0.05	0.25	0.002	0.010
B	0.30 (typ)		0.012 (typ)	
C	0.18		0.007	
D	2.90	3.10	0.114	0.122
E	2.90	3.10	0.114	0.122
e	0.65 BSC		0.025 BSC	
H	4.78	4.98	0.188	0.196
L	0.52	0.54	0.017	0.025
# per tube	80 pieces*			
# per tape and reel	4000 pieces			
Controlling dimension: inches				

* This is an approximate amount which may vary.



Package Dimensions for MSOP-8